

CPD69-CMR1-06M General Purpose Rectifier Die 1.0 Amp, 600 Volt

The CPD69-CMR1-06M is a silicon 1.0 Amp, 600 Volt general purpose rectifier ideal for all types of commercial, industrial, entertainment, and computer applications.

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AN	ODE	

Die Size	42.5 x 42.5 MILS			
Die Thickness	11.0 MILS			
Anode Bonding Pad Size	24 x 24 MILS			
Top Side Metalization	Ni/Au – 5,000Å/1,350Å			
Back Side Metalization	Ni/Au – 5,000Å/1,350Å			
Scribe Alley Width	2.76 MILS			
Wafer Diameter	4 INCHES			
Gross Die Per Wafer	5,915			

MECHANICAL SPECIFICATIONS:

BACKSIDE CATHODE R1

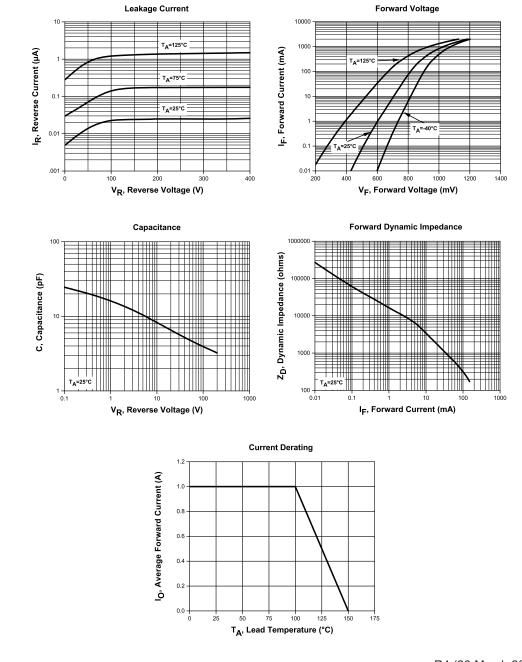
MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS				
Peak Repetitive Reverse Voltage	V _{RRM}	600	V				
DC Blocking Voltage	VR	600	V				
RMS Reverse Voltage	V _{R(RMS)}	420	V				
Average Forward Current (T _A =100°C)	Ϊο	1.0	А				
Peak Forward Surge Current, tp=8.3ms	IFSM	30	А				
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C				
ELECTRICAL CHARACTERISTICS: (T _A =25°C unless otherwise)							
SYMBOL TEST CONDITIONS	MIN	MAX	UNITS				
I _R V _R =600V		5.0	μA				
V _F I _F =1.0A		1.1	V				
C _J V _R =0, f=1.0MHz		40	pF				

R4 (26-March 2019)

CPD69-CMR1-06M Typical Electrical Characteristics



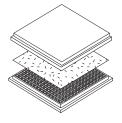
www.centralsemi.com



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BARE DIE PACKING OPTIONS



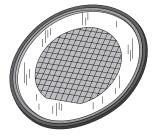


BARE DIE IN TRAY (WAFFLE) PACK

- CT: Singulated die in tray (waffle) pack. (example: CP211-PART NUMBER-CT)
- CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes). (example: CP211-<u>PART NUMBER</u>-CM)

UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked. (example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked. (example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications: www.centralsemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- · Environmental regulation compliance
- Customer specific screening
- · Up-screening capabilities

· Custom product packing

Custom bar coding for shipments

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

REQUESTING PRODUCT PLATING

- If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when 1. ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

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